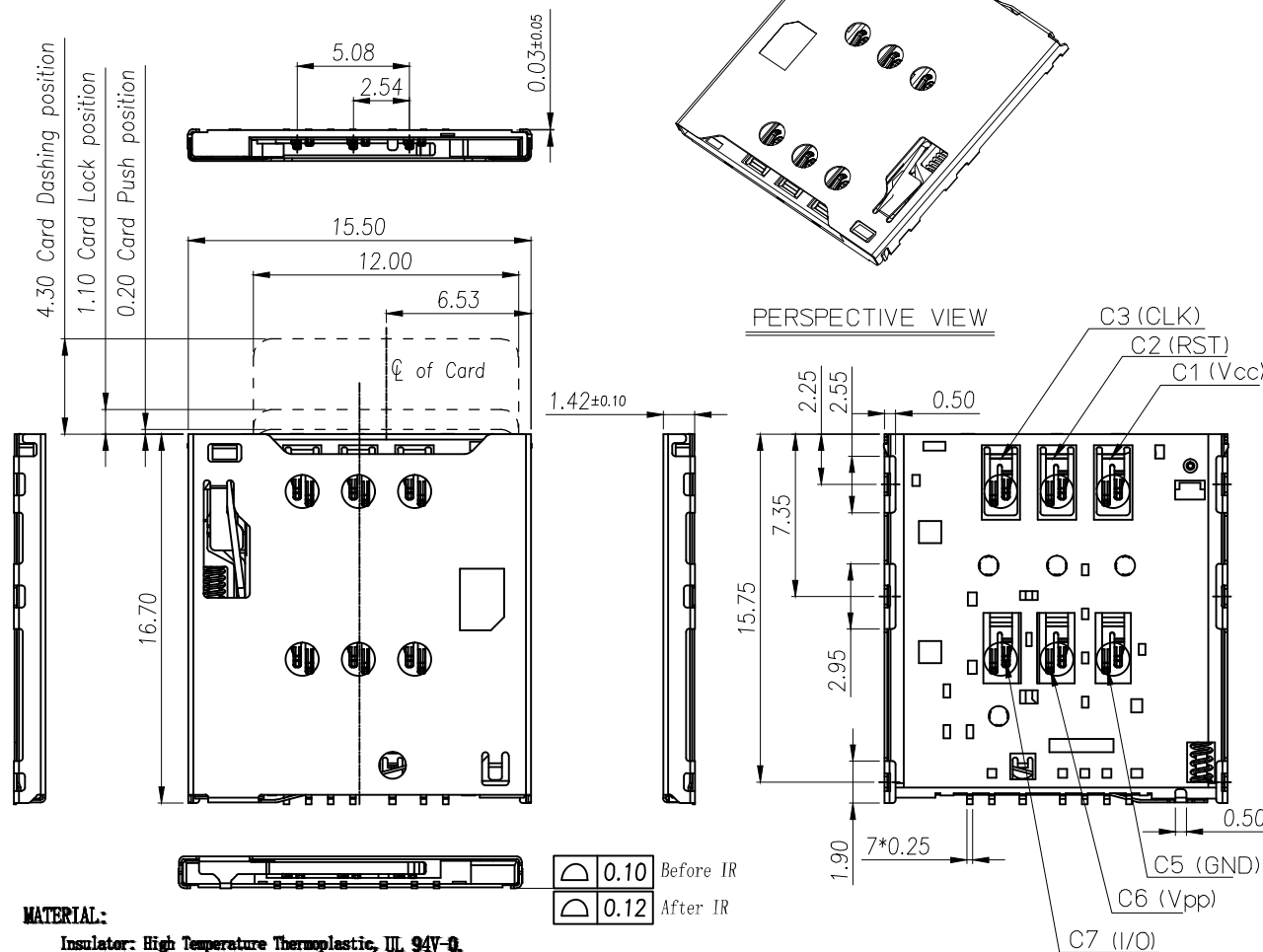


REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	01/12'20	YZZ		HAIYONG



MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0

Contact: Copper Alloy

SHELL: SUS

PLATING:

Contact: Plated 50u" Ni Overall Contact Au 1U

Shell: Plated 50u" Ni Overall

Plated In Au Selective Contact Area

Electrical:

Current Rating : 0.5mA AC/DC max.

Voltage Rating :125V AC/DC

Ambient Temperature Range :-20° C~+60° C

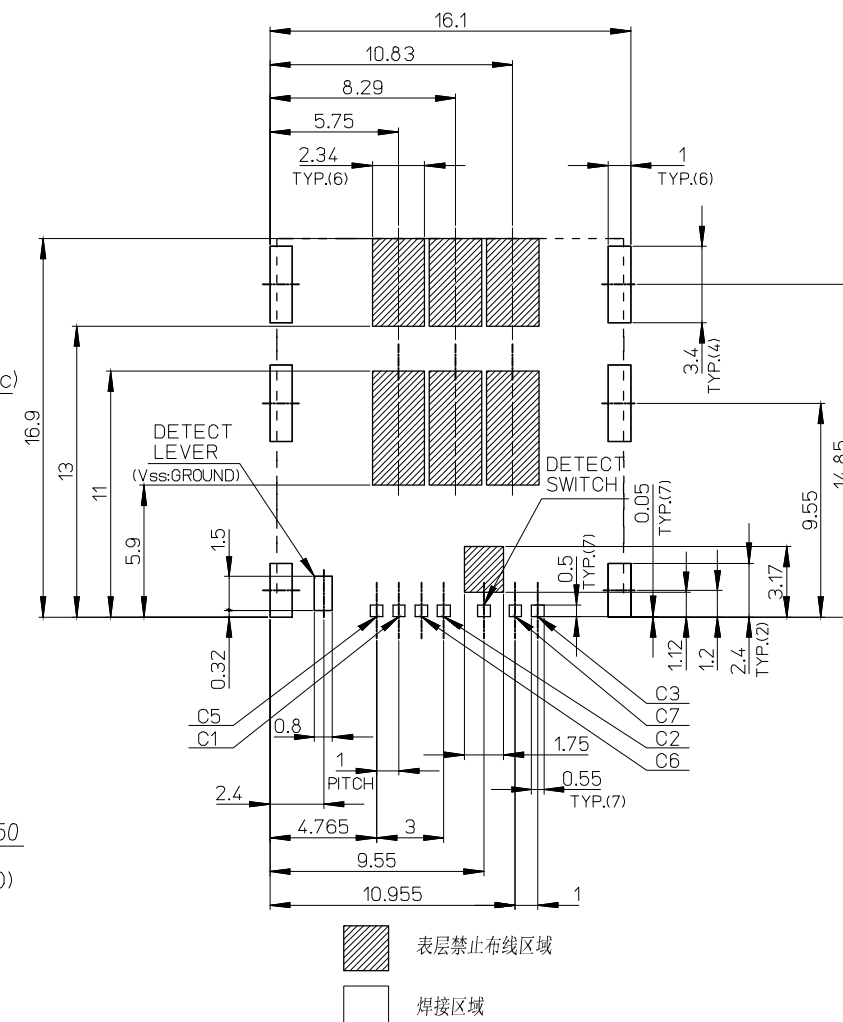
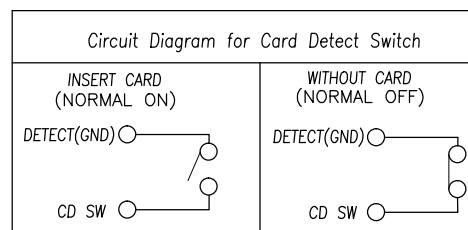
Storage Temperature Range : -40° C~+70° C

Ambient Humidity Range :95% R.H. Max.

Insulation Resistance: 1000M min./500VDC

产品耐湿温度: 260

Mating Cycles: 3000 Min Insertions



RECOMMENDED PCB PATTERN LAYOUT

(GENERAL TOLERANCE : ± 0.05)

MILLIMETERS	INCH	UNITS	 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.							
X° ± 2°	X° ± 2°	MAT'L								
.X ±0.30	.XX ±0.012	SEE NOTES								
.XX ±0.25	.XXX ±0.010	FINISH								
.XXX±0.10	.XXXX±0.004	SEE NOTES	PART NUMBER: XB-102313952	TITLE: 1.42H Push Push Micro SIM CARD.						
		QTY	APPD: HAIYONG	DWG NO.: C-102313952-00						
		SEE NOTES	CHKD: --							
			DR: YZZ	 <table><tr><th>SCALE</th><th>SHEET</th><th>REV.</th></tr><tr><td>1:1</td><td>1/1</td><td>AO</td></tr></table>	SCALE	SHEET	REV.	1:1	1/1	AO
SCALE	SHEET	REV.								
1:1	1/1	AO								